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2821

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: LOO, Mike C.

Docket No.: **US018154**

PTO Application No.: 10/001271 Conf.: 2095

Art Unit: 2827

Date Filed: 12/04/2001

Examiner: Dinh, Tuan

Title: Optimum Power And Ground Bump Pad And Bump Patterns For Flip Chip Packaging

Mail Stop DD

Commissioner for Patents

P.O. Box 1450, Alexandria, VA 22313-1450

**TRANSMITTAL OF  
INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §1.97**

Sir:

Enclosed in this transmittal is an "Information Disclosure Statement by Applicant" and a copy of each of the documents listed thereon. These documents are considered to be relevant in that they have been cited as an "X" or "Y" document in a foreign Patent Office search report on a foreign counterpart application, a copy of which report is also enclosed.

☒ I hereby certify that these documents were cited in said search report not more than three (3) months prior to the filing of this information disclosure statement.

This disclosure is not an admission that any of these documents is material to or even prior art with respect to the above-referenced application.

The Commissioner is hereby requested and authorized pursuant to 37 CFR §1.136(a)(3), to treat any concurrent or future reply in this application requiring a petition for extension of time for its timely submission, as incorporating a petition for extension of time for the appropriate length of time. Please charge any additional fees which may now or in the future be required in this application, including extension of time fees, but excluding the issue fee unless explicitly requested to do so, and credit any overpayment, to Deposit Account No. 14-1270.

Date: 12/15/03

Respectfully submitted,

By

  
Chris Horgan, Reg. No. 40,394

Philips Electronics North America Corp.

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage for first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" on the date indicated below.

(Date)

12/23/03

(Signature)

(Name) Daniel L. Michalek



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**APPOINTMENT OF ASSOCIATES**

Sir:

The undersigned Attorney of Record hereby revokes all prior appointments (if any) of Associate Attorney(s) or Agent(s) in the above-captioned case and appoints:

Chris Horgan

Registration No. 40,394;

Edward Blocker

Registration No. 30,245;

Kevin Fortin

Registration No. 35,140;

Kevin Simons

Registration No. 45,110;

Michael J. Ure

Registration No. 33,089; and

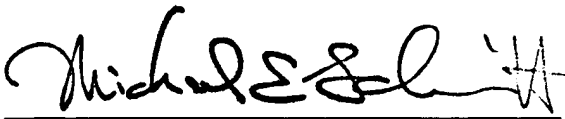
Peter Zawilski

Registration No. 43,305

c/o PHILIPS ELECTRONICS NORTH AMERICA CORPORATION, Corporate Intellectual Property, 1000 West Maude Ave., Sunnyvale, California 94085, his Associate Attorneys/Agents with all the usual powers to prosecute the above-identified application and any division or continuation thereof, to make alterations and amendments therein, and to transact all business in the Patent and Trademark Office connected therewith.

All correspondence concerning this application and the letters patent when granted should be addressed to the undersigned Attorney of Record.

Respectfully,

By 

Michael E. Schmitt, Reg. 36,921

Attorney of Record

Dated at Sunnyvale, California  
on December 6, 2003.



# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Application Number	10/001271
Filing Date	12/04/2001
First Named Inventor	LOO, Mike C.
Art Unit	2827
Examiner Name	Dinh, Tuan
Attorney Docket Number	US018154

## U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Document Number No.-Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns Lines, Where Relevant Passages or Relevant Figures Appear
		US- 6 064 113	05-16-2000	KIRKMAN, SCOTT L.	
		US-			
		US-			
		US-			
		US-			
		US-			

## FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Document Number (ctry <sup>3</sup> -no. <sup>4</sup> -kind <sup>5</sup> , if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of cited document	Pages, Columns Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		EP 0 921 567	06-09-1999	MICHIO, HORIUCHI		

## NON-PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in capital letters), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>6</sup>

Examiner  
Signature

Date  
Considered

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Unique citation designation number. <sup>2</sup> See attached Kinds of U.S. Patent Documents. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to place a check mark here if English language Translation is attached.